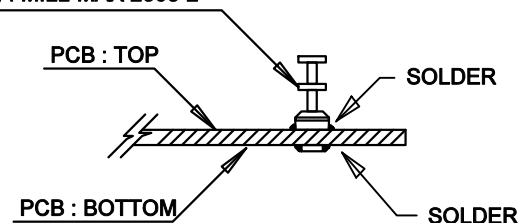


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	4	PRODUCTION	PW	10-10-17

NOTES: UNLESS OTHERWISE SPECIFIED


1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELCIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
6. INSTALL TURRETS AS SHOWN BELOW:

(3PLCS) : MILL-MAX 2308-2



7. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.
8. INSTALL JUMPERS FOR JP1 AND JP2 AS SHOWN BELOW:



APPROVALS		 <div> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.Linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>		
PCB DES.	NC			
APP ENG.	PW			
		TITLE: TOP ASSEMBLY DRAWING:		
		isoSPI AND ISOLATED CAN ARDUINO BOARD		
		SIZE	IC NO. LTC6820, LTM2889	REV.
		N/A	DEMO CIRCUIT 2617A	04
SCALE = NONE		SHT 1 of 2		